

Amr Baher Darwish
Magdy Ali El-Moursy
Mohamed Amin Dessouky

Transaction- Level Power Modeling

 Springer

Transaction-Level Power Modeling

Amr Baher Darwish · Magdy Ali El-Moursy ·
Mohamed Amin Dessouky

Transaction-Level Power Modeling

 Springer

Amr Baher Darwish
Mentor a Siemens Business
Cairo, Egypt

Magdy Ali El-Moursy
Mentor a Siemens Business
Cairo, Egypt

Mohamed Amin Dessouky
Ain Shams University
Cairo, Egypt

ISBN 978-3-030-24826-0 ISBN 978-3-030-24827-7 (eBook)
<https://doi.org/10.1007/978-3-030-24827-7>

© Springer Nature Switzerland AG 2020

This work is subject to copyright. All rights are reserved by the Publisher, whether the whole or part of the material is concerned, specifically the rights of translation, reprinting, reuse of illustrations, recitation, broadcasting, reproduction on microfilms or in any other physical way, and transmission or information storage and retrieval, electronic adaptation, computer software, or by similar or dissimilar methodology now known or hereafter developed.

The use of general descriptive names, registered names, trademarks, service marks, etc. in this publication does not imply, even in the absence of a specific statement, that such names are exempt from the relevant protective laws and regulations and therefore free for general use.

The publisher, the authors and the editors are safe to assume that the advice and information in this book are believed to be true and accurate at the date of publication. Neither the publisher nor the authors or the editors give a warranty, expressed or implied, with respect to the material contained herein or for any errors or omissions that may have been made. The publisher remains neutral with regard to jurisdictional claims in published maps and institutional affiliations.

This Springer imprint is published by the registered company Springer Nature Switzerland AG
The registered company address is: Gewerbestrasse 11, 6330 Cham, Switzerland

Preface

Transaction-Level Modeling (TLM) is a technique for building and developing designs. TLM introduces abstract modeling of communication schemes between design modules. It provides insights for system-level design at early stages of development. Thus, TLM accelerates the design cycle of System-on-Chip (SoC) in the industry.

A novel methodology, referred to as Transaction-Level Power Modeling (TLPM), is proposed. It is used to evaluate power consumption using TLM. Evaluating power consumption at early phases of product design cycle is important to decrease the number of expensive design iterations. The methodology exploits the existing tools for Register Transfer Level (RTL) simulation, design synthesis, and SystemC prototyping to provide fast and accurate power results. TLPM is performed in two stages: power characterization on RTL and power modeling on TLM. Experimental results reveal both efficiency and accuracy of the TLPM methodology. TLPM speeds up the simulation time by more than two orders of magnitude over RTL, while the error in power estimation is less than 3%.

Cairo, Egypt

Amr Baher Darwish
Magdy Ali El-Moursy
Mohamed Amin Dessouky

Acknowledgements

I would like to express my great gratitude to Prof. Mohamed Dessouky and Dr. Magdy El-Moursy for their continuous guidance and insightful thoughts.

Special thanks to Karim Abo El-Makarem (may his soul rest in peace), Ahmed Aly, AbdelRahman Anwar, Adham Rageh, Ahmed El-Zeiny, and Ahmed Khalil for their contribution and qualification of methodology on different designs.

Finally, I am grateful to my family for assistance and inspiration to accomplish this book.

Contents

1	Introduction	1
1.1	Motivation	1
1.2	Contribution	2
1.2.1	Power Characterization	2
1.2.2	Power Modeling in TLM	3
1.2.3	TLPM Methodology	3
1.3	Book Summary	3
	References	4
Part I Background		
2	Fundamental Concepts	9
2.1	Introduction	9
2.2	Design Modeling	9
2.2.1	Introduction	9
2.2.2	Design Abstraction Levels	10
2.2.3	TLM Design Abstraction	11
2.3	SystemC	12
2.3.1	Scope	12
2.3.2	Purpose	12
2.3.3	SystemC Example	12
2.4	Transaction-Level Modeling	14
2.4.1	Overview	14
2.4.2	TLM 2.0 Interfaces	26
2.4.3	TLM-2.0 Global Quantum	34
2.4.4	Combined TLM-2.0 Interfaces	34
2.4.5	TLM-2.0 Sockets	34
2.4.6	TLM-2.0 Phases	35
2.4.7	Base Protocol	35
2.4.8	TLM-2.0 Examples	36

2.5	Universal Verification Methodology	39
2.5.1	Introduction	39
2.5.2	Base Classes	40
2.5.3	UVM Factory	41
2.5.4	Predefined Classes	42
2.6	Design Synthesis	43
2.7	Switching Activity Interchange Format	44
2.8	Summary	44
	References	45
3	Power Modeling and Characterization	47
3.1	Introduction	47
3.2	Power Modeling at Different Levels	47
3.2.1	System Level	47
3.2.2	Component Level	48
3.3	Levels of Abstraction in Modeling	49
3.4	Power Characterization	50
3.4.1	Gate-Level Netlist Characterization	50
3.4.2	Hardware Characterization	50
3.4.3	Datasheet-Based Characterization	51
3.4.4	Look-up Tables' Characterization	52
3.5	Performance Overhead	52
3.6	Power Evaluation	52
3.6.1	Power Analysis Flow	53
3.7	Summary	54
	References	55
 Part II Transaction-Level Power Modeling		
4	Transaction-Level Power Modeling Methodology	61
4.1	Introduction	61
4.2	TLPM Flow	61
4.2.1	Overview	61
4.2.2	Power Estimation Using TLPM	62
4.3	Power Characterization	63
4.3.1	TLPM Power Characterization Flow	63
4.3.2	Correlation Matrix Example	66
4.3.3	EDA Tools for Power Characterization	66
4.4	TLPM Implementation and Simulation	72
4.4.1	TLPM Implementation and Simulation Flow	73
4.4.2	Power Model Example	80
4.4.3	EDA Tools for TLPM Implementation Phase	81
4.5	Summary	85
	References	86

- 5 Experimental Results** 87
 - 5.1 Introduction 87
 - 5.2 Design Environment 87
 - 5.3 Timer SP804 Experiment 87
 - 5.3.1 Design Information 87
 - 5.3.2 Design Configuration 88
 - 5.3.3 Design Interface 90
 - 5.3.4 Design Signals 90
 - 5.3.5 Registers of the Design 91
 - 5.3.6 TLPM Results 92
 - 5.4 ZYNQ-7000 SoC Experiment 96
 - 5.4.1 Design Information 96
 - 5.4.2 TLPM Results 102
 - 5.5 Summary 106
 - References 106
- 6 Conclusions and Future Work** 107
 - 6.1 Conclusions 107
 - 6.2 Future Work 108
- Index** 109

About the Authors

Amr Baher Darwish received his B.Sc. and M.Sc. degrees in Electronics Engineering from Ain Shams University, Cairo, Egypt, in 2011 and 2017, respectively. In 2011, he worked as Design Application Engineer for RF/AMS team, Intel Corporation, Cairo, Egypt. Between November 2013 and May 2016, he was Quality Assurance Engineer in IC Verification Solutions Department at Mentor, a Siemens business, Cairo, Egypt. During June 2016 and April 2018, he worked as Backline Customer Support Engineer in the same company. Between October 2017 and March 2019, he worked as Senior Quality Assurance Engineer in Mentor. Currently, he is Questa SIM Product Engineer at Mentor, a Siemens business, Cairo, Egypt. He has published journal and conference papers in dynamic power estimation.

Magdy Ali El-Moursy received the B.S. degree in electronics and communications engineering (with honors) and the Master's degree in computer networks from Cairo University, Cairo, Egypt, in 1996 and 2000, respectively, and the Master's and the Ph.D. degrees in electrical engineering in the area of high-performance VLSI/IC design from University of Rochester, Rochester, NY, USA, in 2002 and 2004, respectively. In summer of 2003, he was with STMicroelectronics, Advanced System Technology, San Diego, CA, USA. Between September 2004 and September 2006 he was a Senior Design Engineer at Portland Technology Development, Intel Corporation, Hillsboro, OR, USA. During September 2006 and February 2008 he was assistant professor in the Information Engineering and Technology Department of the German University in Cairo (GUC), Cairo, Egypt. Between February 2008 and October 2010 he was Technical Lead in the Mentor Hardware Emulation Division, Mentor Graphics Corporation, Cairo, Egypt.

Dr. El-Moursy is currently Engineering Manager in Integrated Circuits Verification Systems Division, Mentor, A Siemens Business and Associate Professor in the Microelectronics Department, Electronics Research Institute, Cairo, Egypt. He is Associate Editor in the Editorial Board of Elsevier Microelectronics Journal, Journal of Circuits, Systems, and Computers, and International Journal of Circuits and Architecture Design and Technical Program Committee of many IEEE

Conferences such as ISCAS, ICAINA, PacRim CCCSP, ISESD, SIECPC, and IDT. His research interest is in Networks-on-Chip/System-on-Chip, interconnect design and related circuit level issues in high performance VLSI circuits, clock distribution network design, digital ASIC circuit design, VLSI/SoC/NoC design and validation/verification, circuit verification and testing and low power design. He is the author of around 90 papers, six book chapters, and four books in the fields of high speed and low power CMOS design techniques and NoC/SoC.

Mohamed Amin Dessouky received the B.Sc. and M.Sc. degrees in electrical engineering from the University of Ain Shams, Cairo, Egypt, in 1992 and 1995, respectively, and the Ph.D. degree in electrical engineering from the University of Paris VI, Paris, France, in 2001. In 1992 he joined the Electronics and Electrical Communications Engineering Department, University of Ain Shams, where he is now a full Professor. From 2010 to 2013 he was the director of the Integrated Circuits Lab at the same department. Prof. Dessouky was a visiting professor at the University of Paris VI in 2002 and 2004. From 2004 to 2010, he was on leave to Mentor Graphics Egypt, where he has been leading a mixed-signal design team responsible for the design of high-speed serial links. He also participated in the research and development of an EDA tool for technology porting of analog circuit designs. He is currently a staff Engineer at the same company. He also served in the Technical Committees of many IEEE Conferences such as DATE, SMACD, IDT and ICM. His research interests include custom digital design, ultra-low voltage design, analog-to-digital converters and CAD for analog and mixed-signal design. Prof. Dessouky holds four US patents and has published several journal and conference papers in addition to a book chapter on analog layout design porting.

Abbreviations

AMBA	Advanced Microcontroller Bus Architecture
AP SoC	All Programmable SoC
APB	Advanced Peripheral Bus
AT	Approximately-time
CA	Cycle-Accurate
DMI	Direct Memory Interface
DUT	Design Under Test
EB	Energy per Byte
EMIO	Extended Multiplexed I/O
ESL	Electronic System Level
FPGA	Field-Programmable Gate Array
FRC	Free Running Counter
GL	Gate Level
GPIO	General Purpose I/O
GUI	Graphical User Interface
HDL	Hardware Description Language
HTLP	Hierarchical Transaction Level Power
HW	Hardware
I2C	Inter Integrated Circuit
IC	Integrated Circuit
LT	Loosely-timed
MIO	Multiplexed I/O
MISO	Master Input Slave Output
MOSI	Master Output Slave Input
OOP	Object-Oriented Programming
PKtool	Power Kernel Tool
PL	Programmable Logic
PPC	Performance Optimization With Enhanced RISC – Performance Computing
PS	Processing System

PV	Programmer View
PVT	Programmer View Plus Timing
RTL	Register Transfer Level
RXFIFO	Receiver First In First Out
SAIF	Switching Activity Interchange Format
SoC	System-on-Chip
SPI	Serial Peripheral Interface
SW	Software
TLM	Transaction Level Modeling
TLPM	Transaction Level Power Modeling
TXFIFO	Transmitter First In First Out
UART	Universal Asynchronous Receiver Transmitter
UPF	Unified Power Format
UVM	Universal Verification Methodology
VCD	Value Change Dump